

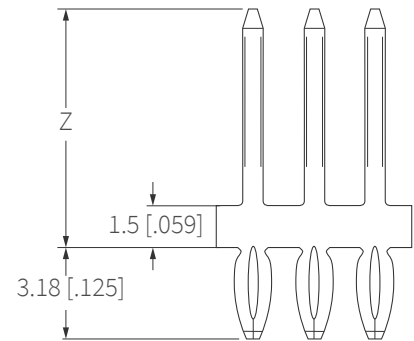
## 1.5 BLADE PRESS-FIT TERMINAL SPECIFICATIONS

TYPE	PART NUMBER	MATERIAL	SIZE	Z LENGTH		PCB HOLE SIZE	CARRIER TYPE	CURRENT CAPACITY STANDARD	CURRENT CAPACITY HI-TEMP
				MM	INCH				
1.5 Blade	7-V5068-001ST	Hi Temp	1.5 x .64	16.00	0.630	A	Side Carrier	7A	15A
	7-V5068-011TT	Hi Temp	1.5 x .64	14.70	0.579	A	Side Carrier	8A	16A
	7-V5077-001TA	Hi Temp	1.5 x .64	11.75	0.463	A	Side Carrier	10A	20A

### NOTE:

- Current Carrying Capacity (Current Rating) for  $\Delta T = 30^{\circ}\text{C}$  Heat Rise
- Current Carrying Capacity (Current Rating) for C42520 is defined per: SAE/USCAR-2 - Revision 5 - Section 5.3.3, EIA Publication 364 - Procedure 70 thru the testing
- Current Carrying Capacities (Current Rating) for C19010 are defined using C42520 data and theoretical formula
- All current ratings must be verified during validation testing of the final assembly

### Side Carrier



## PRESS-FIT PCB HOLE SIZE REQUIREMENTS

HOLE SIZE	COMPONENT THICKNESS	FINISHED HOLE DIAMETER	DESCRIPTION	PC BOARD DIMENSIONS
A	0.64 mm	1.05 mm	Drilled Hole	1.15 ± 0.025 mm
			Copper Plating	
			Plating Thickness	25 µm min
			Hole Diameter	1.05 ± 0.05 mm
			Finished Hole	
			Tin Plating Thickness	2 µm-8 µm
			Plated Hole Diameter	1.05 ± 0.05 mm
			Precious metal Plated (Note 2)	1.05 ± 0.05 mm

### NOTE:

1. Tin thickness applies to tin-lead and lead free plating.

2. Precious metal plating types:

#### Immersion Au:

0.08 µm-0.13 µm [3 µin-5 µin] Gold over  
3.8 µm-7.6 µm [150 µin-300 µin] Nickel

#### Immersion Ag:

0.2 µm-0.5 µm [8 µin -20 µin]